

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3677	438/584.ccls. or 438/597.ccls. or 438/612.ccls. or 438/613.ccls. or 438/614.ccls. or 438/652.ccls. or 438/654.ccls. or 438/669.ccls. or 438/670.ccls. or 438/674.ccls.	USPAT	OR	ON	2005/01/28 14:37
S2	696	S1 and ((nickel or Ni) and (copper or Cu) and (gold or Au))	USPAT	OR	ON	2005/01/28 14:40
S3	281	438/584.ccls.	USPAT	OR	ON	2005/01/28 14:37
S4	1778	438/597.ccls. or 438/612.ccls. or 438/613.ccls.	USPAT	OR	ON	2005/01/28 14:37
S5	1113	438/614.ccls. or 438/652.ccls. or 438/654.ccls.	USPAT	OR	ON	2005/01/28 14:38
S6	993	438/669.ccls. or 438/670.ccls. or 438/674.ccls.	USPAT	OR	ON	2005/01/28 14:39
S7	97016	((nickel or Ni) and (copper or Cu) and (gold or Au)) and (substrate or chip or wafer or support or base or die or dice or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:42
S8	15151	S7 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:42
S9	4667	S8 and (solder with contact)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:43
S10	4405	S9 not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:43
S11	1075	S10 and metallization	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:43

S12	280	S11 and (metallization with (au or gold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 14:47
S13	49	BRINTZINGER .in.	USPAT	OR	ON	2005/01/28 14:48
S14	20	UHLENDORF.in.	USPAT	OR	ON	2005/01/28 14:48
S15	772	SCHENK.in.	USPAT	OR	ON	2005/01/28 14:49
S16	1	(andre with SCHENK).in.	USPAT	OR	ON	2005/01/28 14:49
S17	0	WOLLANKE.in.	USPAT	OR	ON	2005/01/28 15:24
S19	3	(("6838368") or ("6809020") or ("6413845")).PN.	USPAT	OR	OFF	2005/01/28 15:26